

Via Facsimile (703) 872-9306

Serial No. 10/689,936

IIZ.003D2C

Amendment Under 37 C.F.R. 1.312 dated July 1, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi

Group Art Unit: 2823

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Serial No.: 10/689,936

Examiner: F. Toledo

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Filed: October 22, 2003

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For: **METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS
INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS**

AMENDMENT UNDER 37 C.F.R. 1.312

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Sir:

Responsive to the Notice of Allowance dated June 15, 2005, the following amendments and remarks are respectfully submitted in connection with the above-identified application under 37 C.F.R. 1.312.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.

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